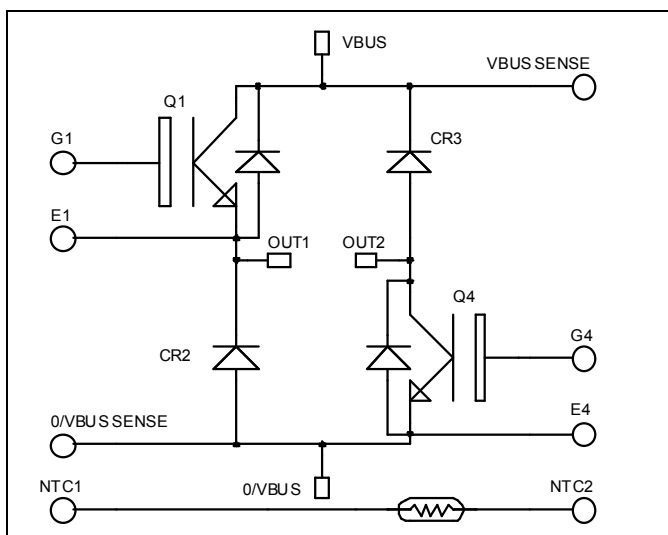


Asymmetrical - Bridge NPT IGBT Power Module

$V_{CES} = 1200V$
 $I_C = 75A @ T_c = 80^\circ C$



Application

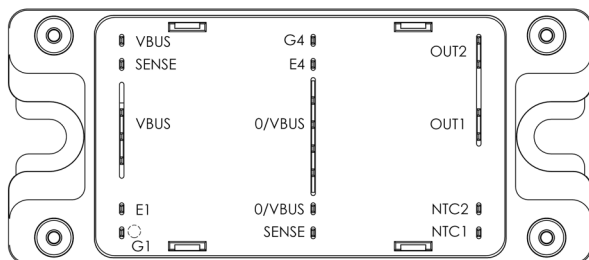
- Welding converters
- Switched Mode Power Supplies
- Uninterruptible Power Supplies
- Motor control

Features

- Non Punch Through (NPT) Fast IGBT
 - Low voltage drop
 - Low tail current
 - Switching frequency up to 50 kHz
 - Soft recovery parallel diodes
 - Low diode VF
 - Low leakage current
 - RBSOA and SCSOA rated
- Kelvin emitter for easy drive
- Very low stray inductance
 - Symmetrical design
 - Lead frames for power connections
- Internal thermistor for temperature monitoring
- High level of integration

Benefits

- Outstanding performance at high frequency operation
- Stable temperature behavior
- Very rugged
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- Solderable terminals both for power and signal for easy PCB mounting
- Easy paralleling due to positive TC of V_{CESat}
- Low profile
- RoHS compliant



Absolute maximum ratings

| Symbol | Parameter | Max ratings | Unit |
|-----------|---------------------------------------|---------------------|--------------|
| V_{CES} | Collector - Emitter Breakdown Voltage | 1200 | V |
| I_C | Continuous Collector Current | $T_c = 25^\circ C$ | A |
| | | $T_c = 80^\circ C$ | |
| I_{CM} | Pulsed Collector Current | $T_c = 25^\circ C$ | 150 |
| V_{GE} | Gate - Emitter Voltage | ± 20 | V |
| P_D | Maximum Power Dissipation | $T_c = 25^\circ C$ | 500 |
| RBSOA | Reverse Bias Safe Operating Area | $T_j = 150^\circ C$ | 150A @ 1200V |

CAUTION: These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed. See application note APT0502 on www.microsemi.com

All ratings @ $T_j = 25^\circ\text{C}$ unless otherwise specified

Electrical Characteristics

| Symbol | Characteristic | Test Conditions | | Min | Typ | Max | Unit |
|---------------|--------------------------------------|--|---|-----|------------|------------|---------------|
| I_{CES} | Zero Gate Voltage Collector Current | $V_{GE} = 0V$ $V_{CE} = 1200V$ | $T_j = 25^\circ\text{C}$ $T_j = 125^\circ\text{C}$ | | | 250 500 | μA |
| $V_{CE(sat)}$ | Collector Emitter saturation Voltage | $V_{GE} = 15V$ $I_C = 75A$ | $T_j = 25^\circ\text{C}$ $T_j = 125^\circ\text{C}$ | | 3.2 3.9 | 3.7 | V |
| $V_{GE(th)}$ | Gate Threshold Voltage | $V_{GE} = V_{CE}, I_C = 2.5\text{ mA}$ | | 4.5 | | 6.5 | V |
| I_{GES} | Gate – Emitter Leakage Current | $V_{GE} = \pm 20V, V_{CE} = 0V$ | | | | ± 500 | nA |

Dynamic Characteristics

| Symbol | Characteristic | Test Conditions | | Min | Typ | Max | Unit |
|--------------|------------------------------|---|---------------------------|-----|-----|-----|------|
| C_{ies} | Input Capacitance | $V_{GE} = 0V$ | | | 5.1 | | nF |
| C_{oes} | Output Capacitance | $V_{CE} = 25V$ | | | 0.7 | | |
| C_{res} | Reverse Transfer Capacitance | $f = 1\text{MHz}$ | | | 0.4 | | |
| $T_{d(on)}$ | Turn-on Delay Time | Inductive Switching (25°C) $V_{GE} = 15V$ $V_{Bus} = 600V$ $I_C = 75A$ $R_G = 7.5\Omega$ | | | 120 | | ns |
| T_r | Rise Time | | | | 50 | | |
| $T_{d(off)}$ | Turn-off Delay Time | | | | 310 | | |
| T_f | Fall Time | | | | 20 | | |
| $T_{d(on)}$ | Turn-on Delay Time | Inductive Switching (125°C) $V_{GE} = 15V$ $V_{Bus} = 600V$ $I_C = 75A$ $R_G = 7.5\Omega$ | | | 130 | | ns |
| T_r | Rise Time | | | | 60 | | |
| $T_{d(off)}$ | Turn-off Delay Time | | | | 360 | | |
| T_f | Fall Time | | | | 30 | | |
| E_{on} | Turn-on Switching Energy | $V_{GE} = 15V$ $V_{Bus} = 600V$ | $T_j = 125^\circ\text{C}$ | | 9 | | mJ |
| E_{off} | Turn-off Switching Energy | $I_C = 75A$ $R_G = 7.5\Omega$ | $T_j = 125^\circ\text{C}$ | | 4 | | |

Diode ratings and characteristics

| Symbol | Characteristic | Test Conditions | | Min | Typ | Max | Unit |
|-----------|---|--|---|------|-------------------|------------|---------------|
| V_{RRM} | Maximum Peak Repetitive Reverse Voltage | | | 1200 | | | V |
| I_{RM} | Maximum Reverse Leakage Current | $V_R = 1200V$ | $T_j = 25^\circ\text{C}$ $T_j = 125^\circ\text{C}$ | | | 250 500 | μA |
| I_F | DC Forward Current | | $T_c = 70^\circ\text{C}$ | | 100 | | A |
| V_F | Diode Forward Voltage | $I_F = 100A$ $I_F = 200A$ $I_F = 100A$ | $T_j = 125^\circ\text{C}$ | | 2.0 2.3 1.8 | 2.5 | V |
| t_{rr} | Reverse Recovery Time | $I_F = 100A$ $V_R = 800V$ $di/dt = 200A/\mu\text{s}$ | $T_j = 25^\circ\text{C}$ $T_j = 125^\circ\text{C}$ | | 420 580 | | ns |
| Q_{rr} | Reverse Recovery Charge | | $T_j = 25^\circ\text{C}$ $T_j = 125^\circ\text{C}$ | | 1.2 5.3 | | μC |

Temperature sensor NTC (see application note APT0406 on www.microsemi.com for more information).

| Symbol | Characteristic | Min | Typ | Max | Unit |
|--------------------|----------------------------|-----|------|-----|------|
| R ₂₅ | Resistance @ 25°C | | 50 | | kΩ |
| B _{25/85} | T ₂₅ = 298.15 K | | 3952 | | K |

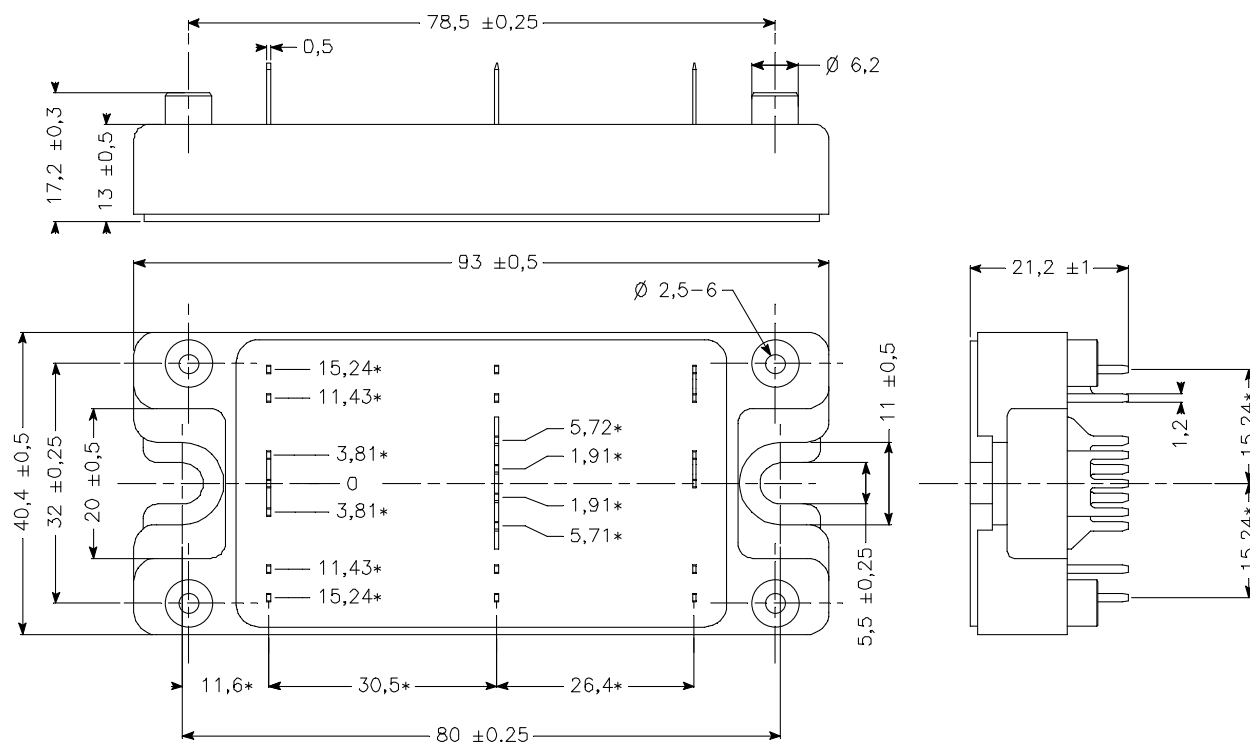
$$R_T = \frac{R_{25}}{\exp \left[B_{25/85} \left(\frac{1}{T_{25}} - \frac{1}{T} \right) \right]}$$

T: Thermistor temperature
 R_T: Thermistor value at T

Thermal and package characteristics

| Symbol | Characteristic | Min | Typ | Max | Unit |
|-------------------|--|-------------|-----|------|------|
| R _{thJC} | Junction to Case Thermal Resistance | IGBT | | 0.25 | °C/W |
| | | Diode | | 0.6 | |
| V _{ISOL} | RMS Isolation Voltage, any terminal to case t=1 min, 50/60Hz | 4000 | | | V |
| T _J | Operating junction temperature range | -40 | | 150 | °C |
| T _{STG} | Storage Temperature Range | -40 | | 125 | |
| T _C | Operating Case Temperature | -40 | | 100 | |
| Torque | Mounting torque | To heatsink | M5 | 4.7 | N.m |
| Wt | Package Weight | | | 160 | g |

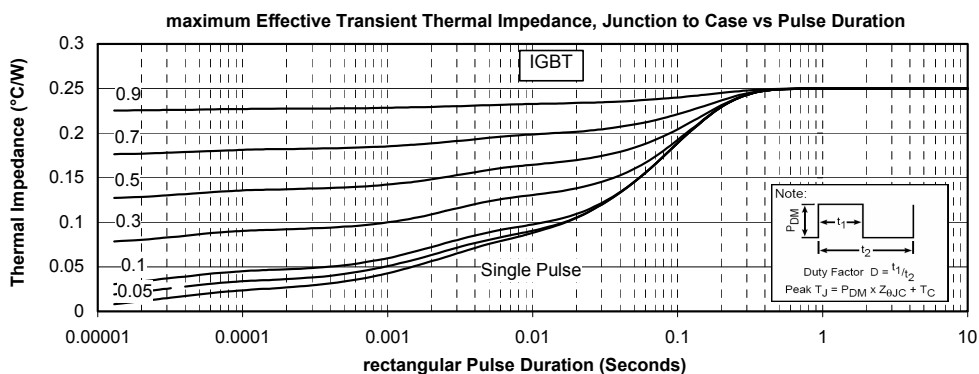
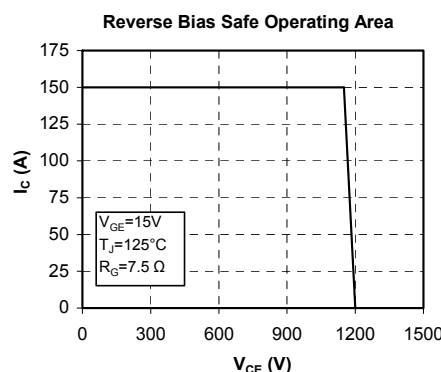
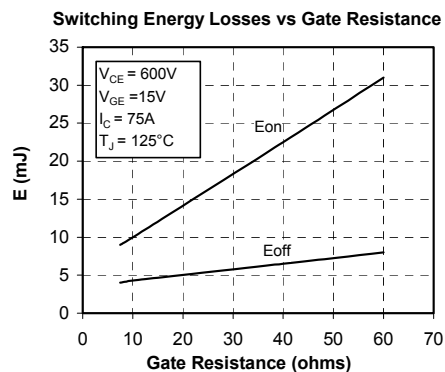
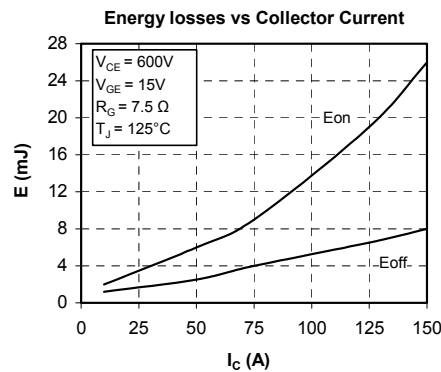
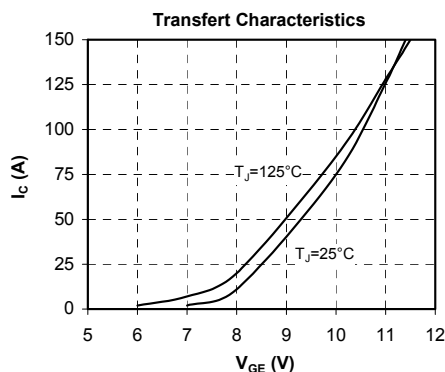
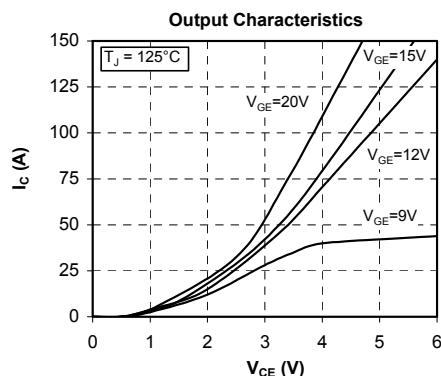
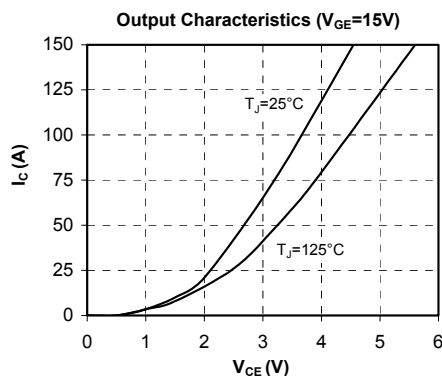
SP4 Package outline (dimensions in mm)

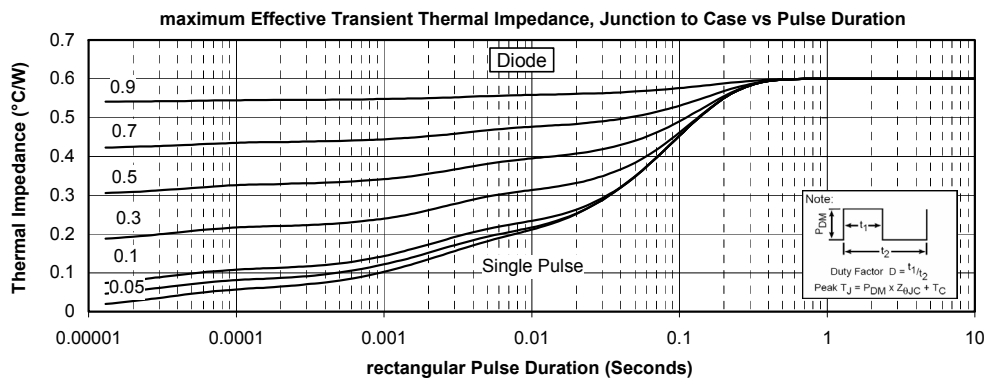
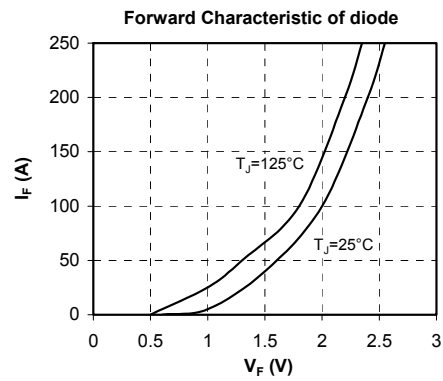
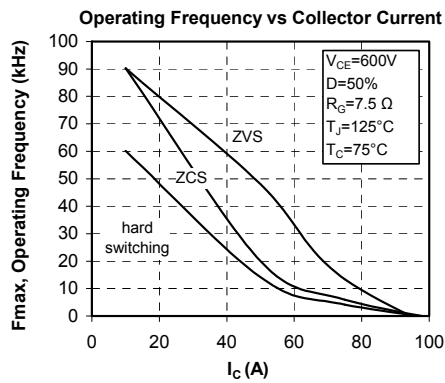


ALL DIMENSIONS MARKED "*" ARE TOLERENCED AS: ± 0.1

See application note APT0501 - Mounting Instructions for SP4 Power Modules on www.microsemi.com

Typical Performance Curve





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